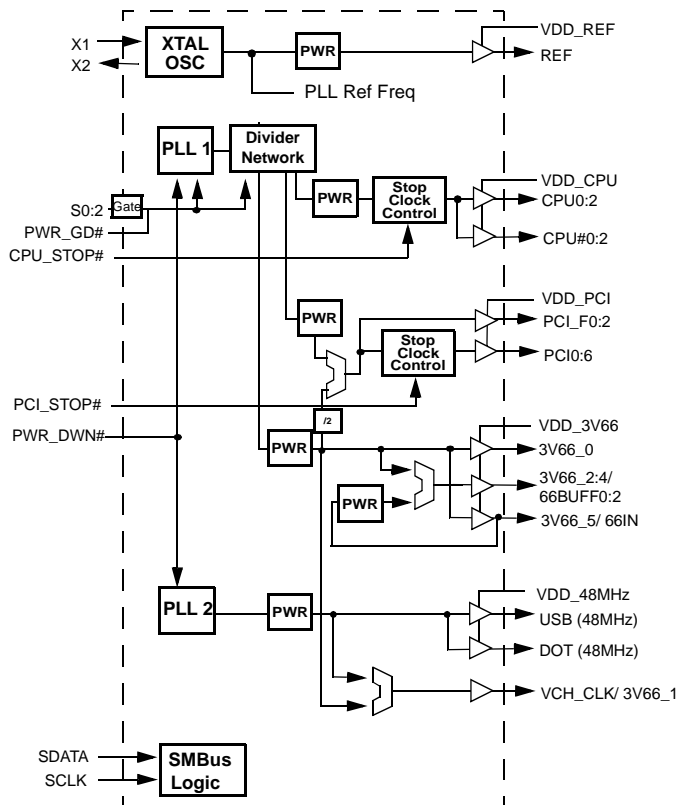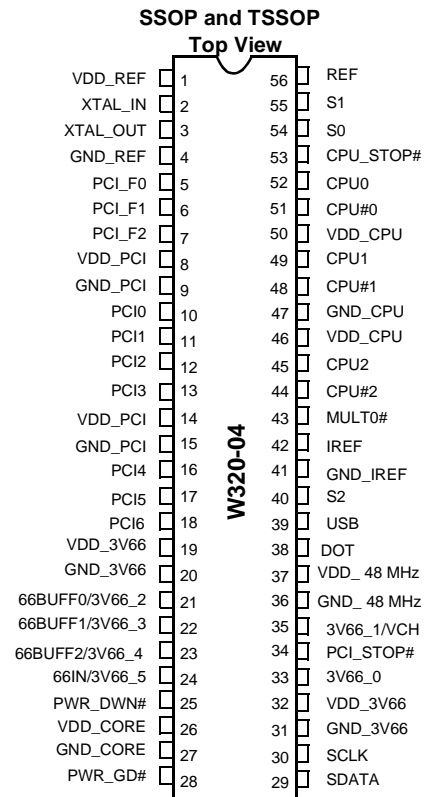# W320-04

## 200-MHz Spread Spectrum Clock Synthesizer/Driver with Differential CPU Outputs

| Features | Benefits |
|---|---|
| • Compliant with Intel® CK-Titan clock synthesizer/driver specifications | Supports next-generation Pentium® processors using differential clock drivers |
| • Multiple output clocks at different frequencies | Motherboard clock generator |
| — Three pairs of differential CPU outputs, up to 200 MHz | — Supports multiple CPUs and a chipset |
| — Ten synchronous PCI clocks, three free-running | — Support for PCI slots and chipset |
| — Six 3V66 clocks | — Supports AGP, DRCG reference, and Hub Link |
| — Two 48-MHz clocks | — Supports USB host controller and graphic controller |
| — One reference clock at 14.318 MHz | — Supports ISA slots and I/O chip |
| — One VCH clock | |
| • Spread Spectrum clocking (down spread) | Enables reduction of electromagnetic interference (EMI) and overall system cost |
| • Power-down features (PCI_STOP#, CPU_STOP# PWR_DWN#) | Enables ACPI-compliant designs |
| • Three Select inputs (Mode select and IC Frequency Select) | Supports up to four CPU clock frequencies |
| • OE and Test Mode support | Enables ATE and "bed of nails" testing |
| • 56-pin SSOP package and 56-pin TSSOP package | Widely available standard package enables lower cost |

## Logic Block Diagram

## Pin Configurations

## Pin Summary

| Name | Pins | Description |
|------|------|-------------|
| REF | 56 | 3.3V 14.318-MHz clock output. |
| XTAL_IN | 2 | 14.318-MHz crystal input. |
| XTAL_OUT | 3 | 14.318-MHz crystal input. |
| CPU, CPU# [0:2] | 44, 45, 48, 49, 51, 52 | Differential CPU clock outputs. |
| 3V66_0 | 33 | 3.3V 66-MHz clock output. |
| 3V66_1/VCH | 35 | 3.3V selectable through SMBus to be 66 MHz or 48 MHz. |
| 66IN/3V66_5 | 24 | 66-MHz input to buffered 66BUFF and PCI or 66-MHz clock from internal VCO. |
| 66BUFF [2:0] /3V66 [4:2] | 21, 22, 23 | 66-MHz buffered outputs from 66Input or 66-MHz clocks from internal VCO. |
| PCI_F [0:2] | 5, 6, 7, | 33-MHz clocks divided down from 66Input or divided down from 3V66. |
| PCI [0:6] | 10, 11, 12, 13, 16, 17, 18 | PCI clock outputs divided down from 66Input or divided down from 3V66. |
| USB | 39 | Fixed 48-MHz clock output. |
| DOT | 38 | Fixed 48-MHz clock output. |
| S2 | 40 | Special 3.3V 3-level input for Mode selection. |
| S1, S0 | 54, 55 | 3.3V LVTTL inputs for CPU frequency selection. |
| IREF | 42 | A precision resistor is attached to this pin, which is connected to the internal current reference. |
| MULT0 | 43 | 3.3V LVTTL input for selecting the current multiplier for the CPU outputs. |
| PWR_DWN# | 25 | 3.3V LVTTL input for Power_Down# (active LOW). |
| PCI_STOP# | 34 | 3.3V LVTTL input for PCI_STOP# (active LOW). |
| CPU_STOP# | 53 | 3.3V LVTTL input for CPU_STOP# (active LOW). |
| PWRGD# | 28 | 3.3V LVTTL input is a level sensitive strobe used to determine when S[2:0] and MULTI0 inputs are valid and OK to be sampled (Active LOW). Once PWRGD# is sampled LOW, the status of this output will be ignored. |
| SDATA | 29 | SMBus compatible SDATA. |
| SCLK | 30 | SMBus compatible SCLK. |
| VDD_REF, VDD_PCI, VDD_3V66, VDD_CPU | 1, 8, 14, 19, 32, 46, 50 | 3.3V power supply for outputs. |
| VDD_48 MHz | 37 | 3.3V power supply for 48 MHz. |
| VDD_CORE | 26 | 3.3V power supply for PLL. |
| GND_REF, GND_PCI, GND_3V66, GND_IREF, VDD_CPU | 4, 9, 15, 20, 31, 36, 41, 47 | Ground for outputs. |
| GND_CORE | 27 | Ground for PLL. |

## Function Table[1]

| S2 | S1 | S0 | CPU (MHz) | 3V66[0:1] (MHz) | 66BUFF[0:2]/ 3V66[2:4] (MHz) | 66IN/3V66_5 (MHz) | PCI_F/PCI (MHz) | REF0(MHz) | USB/DOT (MHz) | Notes: |
|---|---|---|---|---|---|---|---|---|---|---|
| 1 | 0 | 0 | 66 MHz | 66 MHz | 66IN | 66 MHz Input | 66IN/2 | 14.318 MHz | 48 MHz | 2, 3, 4 |
| 1 | 0 | 1 | 100 MHz | 66 MHz | 66IN | 66 MHz Input | 66IN/2 | 14.318 MHz | 48 MHz | 2, 3, 4 |
| 1 | 1 | 0 | 200 MHz | 66 MHz | 66IN | 66 MHz Input | 66IN/2 | 14.318 MHz | 48 MHz | 2, 3, 4 |
| 1 | 1 | 1 | 133 MHz | 66 MHz | 66IN | 66 MHz Input | 66IN/2 | 14.318 MHz | 48 MHz | 2, 3, 4 |
| 0 | 0 | 0 | 66 MHz | 66 MHz | 66 MHz | 66 MHz | 33 MHz | 14.318 MHz | 48 MHz | 2, 3, 4 |
| 0 | 0 | 1 | 100 MHz | 66 MHz | 66 MHz | 66 MHz | 33 MHz | 14.318 MHz | 48 MHz | 2, 3, 4 |
| 0 | 1 | 0 | 200 MHz | 66 MHz | 66 MHz | 66 MHz | 33 MHz | 14.318 MHz | 48 MHz | 2, 3, 4 |
| 0 | 1 | 1 | 133 MHz | 66 MHz | 66 MHz | 66 MHz | 33 MHz | 14.318 MHz | 48 MHz | 2, 3, 4 |
| Mid | 0 | 0 | Hi-Z | Hi-Z | Hi-Z | Hi-Z | Hi-Z | Hi-Z | Hi-Z | 1, 5 |
| Mid | 0 | 1 | TCLK/2 | TCLK/4 | TCLK/4 | TCLK/4 | TCLK/8 | TCLK | TCLK/2 | 7, 8, 5 |
| Mid | 1 | 0 | Reserved | Reserved | Reserved | Reserved | Reserved | Reserved | Reserved | – |
| Mid | 1 | 1 | Reserved | Reserved | Reserved | Reserved | Reserved | Reserved | Reserved | – |

## Swing Select Functions

| Mult0 | Board Target Trace/Term Z | Reference R, $IREF = V_{DD}/(3*Rr)$ | Output Current | $V_{OH}$ @ Z |
|---|---|---|---|---|
| 0 | 50Ω | Rr = 221 1%, IREF = 5.00 mA | $I_{OH}$ = 4*IREF | 1.0V @ 50 |
| 1 | 50Ω | Rr = 475 1%, IREF = 2.32 mA | $I_{OH}$ = 6*IREF | 0.7V @ 50 |

## Clock Driver Impedances

| Buffer Name | $V_{DD}$ Range | Buffer Type | Impedance | | |
|---|---|---|---|---|---|
| | | | Min. Ω | Typ. Ω | Max. Ω |
| CPU, CPU# | | Type X1 | | 50 | |
| REF | 3.135–3.465 | Type 5 | 12 | 30 | 55 |
| PCI, 3V66, 66BUFF | 3.135–3.465 | Type 5 | 12 | 30 | 55 |
| USB | 3.135–3.465 | Type 3A | 12 | 30 | 60 |
| DOT | 3.135–3.465 | Type 3B | 12 | 30 | 60 |

## Clock Enable Configuration

| PWR_DWN# | CPU_STOP# | PCI_STOP# | CPU | CPU# | 3V66 | 66BUFF | PCI_F | PCI | USB/DOT | VCOS/ OSC |
|---|---|---|---|---|---|---|---|---|---|---|
| 0 | X | X | IREF*2 | FLOAT | LOW | LOW | LOW | LOW | LOW | OFF |
| 1 | 0 | 0 | ON | FLOAT | ON | ON | ON | OFF | ON | ON |
| 1 | 0 | 1 | ON | LOW | ON | ON | ON | ON | ON | ON |
| 1 | 1 | 0 | ON | ON | ON | ON | ON | OFF | ON | ON |
| 1 | 1 | 1 | ON | ON | ON | ON | ON | ON | ON | ON |

**Note:**
1. TCLK is a test clock driven in on the XTALIN input in test mode.
2. "Normal" mode of operation
3. Range of reference frequency allowed is min. = 14.316, nom. = 14.31818 MHz, max. = 14.32 MHz.
4. Frequency accuracy of 48 MHz must be +167PPM to match USB default.
5. Mid. is defined a Voltage level between 1.0V and 1.8V for three-level input functionality. Low is below 0.8V. High is above 2.0V.
6. Required for DC output impedance verification.
7. These modes are to use the SAME internal dividers as the CPU = 200 MHz mode. The only change is to slow down the internal VCO to allow under clock margining.

## Serial Data Interface (SMBus)

To enhance the flexibility and function of the clock synthesizer, a two signal SMBus interface is provided according to SMBus specification. Through the Serial Data Interface, various device functions such as individual clock output buffers, can be individually enabled or disabled. W320-04 support both block read and block write operations.

The registers associated with the Serial Data Interface initialize to their default setting upon power-up, and therefore use of this interface is optional. Clock device register changes are normally made upon system initialization, if any are required. The interface can also be used during system operation for power management functions.

### Data Protocol

The clock driver serial protocol accepts only block writes from the controller. The bytes must be accessed in sequential order from lowest to highest byte, (most significant bit first) with the

ability to stop after any complete byte has been transferred. Indexed bytes are not allowed.

A block write begins with a slave address and a WRITE condition. The R/W bit is used by the SMBus controller as a data direction bit. A zero indicates a WRITE condition to the clock device. The slave receiver address is 11010010 (D2h).

A command code of 0000 0000 (00h) and the byte count bytes are required for any transfer. After the command code, the core logic issues a byte count which describes number of additional bytes required for the transfer, not including the command code and byte count bytes. For example, if the host has 20 data bytes to send, the first byte would be the number 20 (14h), followed by the 20 bytes of data. The byte count byte is required to be a minimum of 1 byte and a maximum of 32 bytes It may not be 0. *Figure 1* shows an example of a block write.

A transfer is considered valid after the acknowledge bit corresponding to the byte count is read by the controller.
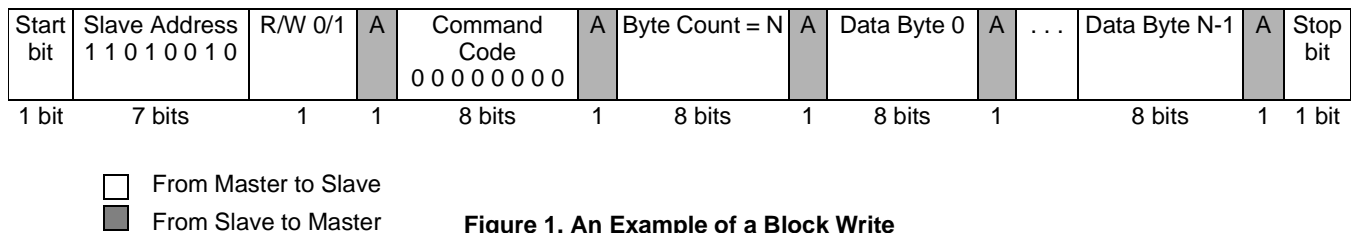
| Start bit | Slave Address<br>1 1 0 1 0 0 1 0 | R/W 0/1 | A | Command Code<br>0 0 0 0 0 0 0 0 | A | Byte Count = N | A | Data Byte 0 | A | . . . | Data Byte N-1 | A | Stop bit |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 1 bit | 7 bits | 1 | 1 | 8 bits | 1 | 8 bits | 1 | 8 bits | 1 | | 8 bits | 1 | 1 bit |

☐ From Master to Slave
■ From Slave to Master

**Figure 1. An Example of a Block Write**

## Data Byte Configuration Map

**Data Byte 0: Control Register (0 = Enable, 1 = Disable)**

| Bit | Affected Pin# | Name | Description | Type | Power On Default |
|---|---|---|---|---|---|
| Bit 7 | 5, 6, 7, 10, 11, 12, 13, 16, 17, 18, 33, 35 | PCI [0:6]<br>CPU[2:0]<br>3V66[1:0] | **Spread Spectrum Enable**<br>0 = Spread Off, 1 = Spread On | R/W | 0 |
| Bit 6 | – | TBD | TBD | R | 0 |
| Bit 5 | 35 | 3V66_1/VCH | **VCH Select 66 MHz/48 MHz**<br>0 = 66 MHz, 1 = 48 MHz | R/W | 0 |
| Bit 4 | 44, 45, 48, 49, 51, 52 | CPU [2:0]<br>CPU# [2:0] | **CPU_STOP#**<br>Reflects the current value of the external CPU_STOP# pin | R | N/A |
| Bit 3 | 10, 11, 12, 13, 16, 17, 18 | PCI [6:0] | **PCI_STOP#**<br>(Does not affect PCI_F [2:0] pins) | R/W | N/A |
| Bit 2 | – | – | **S2**<br>Reflects the value of the S2 pin sampled on power-up | R | N/A |
| Bit 1 | – | – | **S1**<br>Reflects the value of the S1 pin sampled on power-up | R | N/A |
| Bit 0 | – | – | **S0**<br>Reflects the value of the S1 pin sampled on power-up | R | N/A |

**Data Byte 1**

| Bit | Pin# | Name | Description | Type | Power On Default |
|---|---|---|---|---|---|
| Bit 7 | – | N/A | CPU Mult0 Value | R | N/A |
| Bit 6 | 52, 49, 45 | CPU0:2 | Three-State CPU0:2 during power down<br>0 = Normal; 1 = Three-stated | R/W | 0 |
| Bit 5 | 44, 45 | CPU2<br>CPU2# | Allow Control of CPU2 with assertion of CPU_STOP#<br>0 = Not free running; 1 = Free running | R/W | 0 |
| Bit 4 | 48, 49 | CPU1<br>CPU1# | Allow Control of CPU1 with assertion of CPU_STOP#<br>0 = Not free running;1 = Free running | R/W | 0 |
| Bit 3 | 51, 52 | CPU0<br>CPU0# | Allow Control of CPU0 with assertion of CPU_STOP#<br>0= Not free running; 1 = Free running | R/W | 0 |
| Bit 2 | 44, 45 | CPU2<br>CPU2# | CPU2 Output Enable<br>1 = Enabled; 0 = Disabled | R/W | 1 |
| Bit 1 | 48, 49 | CPU1<br>CPU1# | CPU1Output Enable<br>1 = Enabled; 0= Disabled | R/W | 1 |
| Bit 0 | 51, 52 | CPU0<br>CPU0# | CPU0 Output Enable<br>1 = Enabled; 0 = Disabled | R/W | 1 |

**Data Byte 2**

| Bit | Pin# | Name | Pin Description | Type | Power On Default |
|---|---|---|---|---|---|
| Bit 7 | – | N/A | N/A | R | 0 |
| Bit 6 | 18 | PCI6 | PCI6 Output Enable<br>1 = Enabled; 0 = Disabled | R/W | 1 |
| Bit 5 | 17 | PCI5 | PCI5 Output Enable<br>1 = Enabled; 0 = Disabled | R/W | 1 |
| Bit 4 | 16 | PCI4 | PCI4 Output Enable<br>1 = Enabled; 0 = Disabled | R/W | 1 |
| Bit 3 | 13 | PCI3 | PCI3 Output Enable<br>1 = Enabled; 0 = Disabled | R/W | 1 |
| Bit 2 | 12 | PCI2 | PCI2 Output Enable<br>1 = Enabled; 0 = Disabled | R/W | 1 |
| Bit 1 | 11 | PCI1 | PCI1 Output Enable<br>1 = Enabled; 0 = Disabled | R/W | 1 |
| Bit 0 | 10 | PCI0 | PCI0 Output Enable<br>1 = Enabled; 0 = Disabled | R/W | 1 |

**Data Byte 3**

| Bit | Pin# | Name | Pin Description | Type | Power On Default |
|---|---|---|---|---|---|
| Bit 7 | 38 | DOT | DOT 48-MHz Output Enable | R/W | 1 |
| Bit 6 | 39 | USB | USB 48-MHz Output Enable | R/W | 1 |
| Bit 5 | 7 | PCI_F2 | Allow control of PCI_F2 with assertion of PCI_STOP#<br>0 = Free running; 1 = Stopped with PCI_STOP# | R/W | 0 |
| Bit 4 | 6 | PCI_F1 | Allow control of PCI_F1 with assertion of PCI_STOP#<br>0 = Free running; 1 = Stopped with PCI_STOP# | R/W | 0 |
| Bit 3 | 5 | PCI_F0 | Allow control of PCI_F0 with assertion of PCI_STOP#<br>0 = Free running; 1 = Stopped with PCI_STOP# | R/W | 0 |
| Bit 2 | 7 | PCI_F2 | PCI_F2 Output Enable | R/W | 1 |
| Bit 1 | 6 | PCI_F1 | PCI_F1Output Enable | R/W | 1 |
| Bit 0 | 5 | PCI_F0 | PCI_F0 Output Enable | R/W | 1 |

**Data Byte 4**

| Bit | Pin# | Name | Pin Description | Type | Power On Default |
|-----|------|------|-----------------|------|------------------|
| Bit 7 | – | TBD | N/A | R | 0 |
| Bit 6 | – | TBD | N/A | R | 0 |
| Bit 5 | 33 | 3V66_0 | 3V66_0 Output Enable<br>1 = Enabled; 0 = Disabled | R/W | 1 |
| Bit 4 | 35 | 3V66_1/VCH | 3V66_1/VCH Output Enable<br>1 = Enabled; 0 = Disabled | R/W | 1 |
| Bit 3 | 24 | 66IN/3V66_5 | 3V66_5 Output Enable<br>1 = Enable; 0 = Disable<br>NOTE: This bit should be used when pin 24 is configured as 3v66_5 output. Do not clear this bit when pin 24 is configured as 66in input. | R/W | 1 |
| Bit 2 | 23 | 66BUFF2 | 66-MHz Buffered 2 Output Enable<br>1 = Enabled; 0 = Disabled | R/W | 1 |
| Bit 1 | 22 | 66BUFF1 | 66-MHz Buffered 1 Output Enable<br>1 = Enabled; 0 = Disabled | R/W | 1 |
| Bit 0 | 21 | 66BUFF0 | 66-MHz Buffered 0 Output Enable<br>1 = Enabled; 0 = Disabled | R/W | 1 |

**Data Byte 5**

| Bit | Pin# | Name | Pin Description | Type | Power On Default |
|-----|------|------|-----------------|------|------------------|
| Bit 7 | | N/A | N/A | R | 0 |
| Bit 6 | | N/A | N/A | R | 0 |
| Bit 5 | | 66BUFF [2:0] | Tpd 66IN to 66BUFF propagation delay control | R/W | 0 |
| Bit 4 | | 66BUFF [2:0] | | R/W | 0 |
| Bit 3 | | DOT | DOT edge rate control | R/W | 0 |
| Bit 2 | | DOT | | R/W | 0 |
| Bit 1 | | USB | USB edge rate control | R/W | 0 |
| Bit 0 | | USB | | R/W | 0 |

**Byte 6: Vendor ID**

| Bit | Description | Type | Power On Default |
|-----|-------------|------|------------------|
| Bit 7 | Revision Code Bit 3 | R | 0 |
| Bit 6 | Revision Code Bit 2 | R | 0 |
| Bit 5 | Revision Code Bit 1 | R | 0 |
| Bit 4 | Revision Code Bit 0 | R | 0 |
| Bit 3 | Vendor ID Bit 3 | R | 1 |
| Bit 2 | Vendor ID Bit 2 | R | 0 |
| Bit 1 | Vendor ID Bit 1 | R | 0 |
| Bit 0 | Vendor ID Bit 0 | R | 0 |

## Maximum Ratings

(Above which the useful life may be impaired. For user guide-lines, not tested.)

Supply Voltage.................................................–0.5 to +7.0V

Input Voltage............................................ –0.5V to $V_{DD}$+0.5

Storage Temperature (Non-Condensing) ... –65°C to +150°C

Max. Soldering Temperature (10 sec) ...................... +260°C

Junction Temperature............................................. +150°C

Package Power Dissipation.............................................1Ω

Static Discharge Voltage
(per MIL-STD-883, Method 3015) ........................... > 2000V

## Operating Conditions[8] Over which Electrical Parameters are Guaranteed

| Parameter | Description | Min. | Max. | Unit |
|---|---|---|---|---|
| $V_{DD\_REF}$, $V_{DD\_PCI}$, $V_{DD\_CORE}$, $V_{DD\_3V66}$, $V_{DD\_CPU}$, | 3.3V Supply Voltages | 3.135 | 3.465 | V |
| $V_{DD\_48\ MHz}$ | 48-MHz Supply Voltage | 2.85 | 3.465 | V |
| $T_A$ | Operating Temperature, Ambient | 0 | 70 | °C |
| $C_{in}$ | Input Pin Capacitance | | 5 | pF |
| $C_{XTAL}$ | XTAL Pin Capacitance | | 22.5 | pF |
| $C_L$ | Max. Capacitive Load on<br>USBCLK, REF<br>PCICLK, 3V66 | | 20<br>30 | pF |
| $f_{(REF)}$ | Reference Frequency, Oscillator Nominal Value | 14.318 | 14.318 | MHz |

## Electrical Characteristics Over the Operating Range

| Parameter | Description | Test Conditions | | Min. | Max. | Unit |
|---|---|---|---|---|---|---|
| $V_{IH}$ | High-level Input Voltage | Except Crystal Pads. Threshold Voltage for Crystal Pads = $V_{DD}$/2 | | 2.0 | | V |
| $V_{IL}$ | Low-level Input Voltage | Except Crystal Pads | | | 0.8 | V |
| $V_{OH}$ | High-level Output Voltage | USB, REF, 3V66 | $I_{OH}$ = −1 mA | 2.4 | | V |
| | | PCI | $I_{OH}$ = −1 mA | 2.4 | | V |
| $V_{OL}$ | Low-level Output Voltage | USB, REF, 3V66 | $I_{OL}$ = 1 mA | | 0.4 | V |
| | | PCI | $I_{OL}$ = 1 mA | | 0.55 | V |
| $I_{IH}$ | Input HIGH Current | $0 \leq V_{IN} \leq V_{DD}$ | | −5 | 5 | mA |
| $I_{IL}$ | Input LOW Current | $0 \leq V_{IN} \leq V_{DD}$ | | −5 | 5 | mA |
| $I_{OH}$ | High-level Output Current | CPU<br>For $I_{OH}$ =6*IRef Configuration | Type X1, $V_{OH}$ = 0.65V | 12.9 | | mA |
| | | | Type X1, $V_{OH}$ = 0.74V | | 14.9 | |
| | | REF, DOT, USB | Type 3, $V_{OH}$ = 1.00V | −29 | | |
| | | | Type 3, $V_{OH}$ = 3.135V | | −23 | |
| | | 3V66, DOT, PCI, REF | Type 5, $V_{OH}$ = 1.00V | −33 | | |
| | | | Type 5, $V_{OH}$ = 3.135V | | −33 | |
| $I_{OL}$ | Low-level Output Current | REF, DOT, USB | Type 3, $V_{OL}$ = 1.95V | 29 | | mA |
| | | | Type 3, $V_{OL}$ = 0.4V | | 27 | |
| | | 3V66, PCI, REF | Type 5, $V_{OL}$ =1.95 V | 30 | | |
| | | | Type 5, $V_{OL}$ = 0.4V | | 38 | |
| $I_{OZ}$ | Output Leakage Current | Three-state | | | 10 | mA |
| $I_{DD3}$ | 3.3V Power Supply Current | VDD_CORE/VDD3.3 = 3.465V, $F_{CPU}$ = 133 MHz | | | 360 | mA |
| $I_{DDPD3}$ | 3.3V Shut-down Current | VDD_CORE/VDD3.3 = 3.465V and @ IREF = 2.32 mA | | | 25 | mA |
| $I_{DDPD3}$ | 3.3V Shut-down Current | VDD_CORE/VDD3.3 = 3.465V and @ IREF = 5.0 mA | | | 45 | mA |

**Note:Notes:**
8. The voltage on any input or I/O pin cannot exceed te powe pin during power-ujp. Power supply sequencing is NOT required.

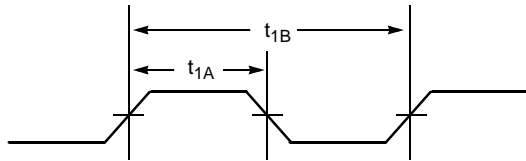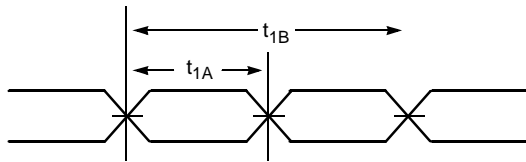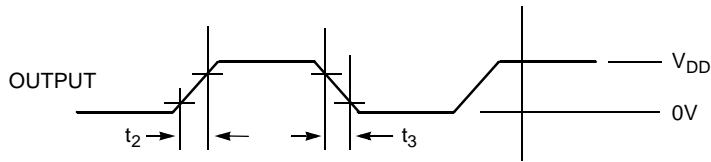## Switching Characteristics[9] Over the Operating Range

| Parameter | Output | Description | Test Conditions | Min. | Max. | Unit |
|---|---|---|---|---|---|---|
| $t_1$ | All | Output Duty Cycle[10] | Measured at 1.5V | 45 | 55 | % |
| $t_3$ | USB, REF, DOT | Falling Edge Rate | Between 2.4V and 0.4V | 0.5 | 2.0 | ns |
| $t_3$ | PCI,3V66 | Falling Edge Rate | Between 2.4V and 0.4V | 1.0 | 4.0 | V/ns |
| $t_5$ | 3V66[0:1] | 3V66-3V66 Skew | Measured at 1.5V | | 500 | ps |
| $t_5$ | 66BUFF[0:2] | 66BUFF-66BUFF Skew | Measured at 1.5V | | 175 | ps |
| $t_6$ | PCI | PCI-PCI Skew | Measured at 1.5V | | 500 | ps |
| $t_7$ | 3V66, PCI | 3V66-PCI Clock Jitter | 3V66 leads. Measured at 1.5V | 1.5 | 3.5 | ns |
| $t_9$ | 3V66 | Cycle-Cycle Clock Jitter | Measured at 1.5V $t_9 = t_{9A} - t_{9B}$ | | 250 | ps |
| $t_9$ | USB, DOT | Cycle-Cycle Clock Jitter | Measured at 1.5V $t_9 = t_{9A} - t_{9B}$ | | 350 | ps |
| $t_9$ | PCI | Cycle-Cycle Clock Jitter | Measured at 1.5V $t_9 = t_{9A} - t_{9B}$ | | 500 | ps |
| $t_9$ | REF | Cycle-Cycle Clock Jitter | Measured at 1.5V $t_9 = t_{9A} - t_{9B}$ | | 1000 | ps |
| **CPU 1.0V Switching Characteristics** | | | | | | |
| $t_2$ | CPU | Rise Time | Measured differential waveform from −0.35V to +0.35V | 175 | 467 | ps |
| $t_3$ | CPU | Fall Time | Measured differential waveform from −0.35V to +0.35V | 175 | 467 | ps |
| $t_4$ | CPU | CPU-CPU Skew | Measured at Crossover | | 150 | ps |
| $t_8$ | CPU | Cycle-Cycle Clock Jitter | Measured at Crossover $t_8 = t_{8A} - t_{8B}$ | | 150 | ps |
| | CPU | Rise/Fall Matching | Measured with test loads[13] | | 325 | mV |
| $V_{oh}$ | CPU | High-level Output Voltage including overshoot | Measured with test loads[12] | 0.92 | 1.45 | V |
| $V_{ol}$ | CPU | Low-level Output Voltage including undershoot | Measured with test loads[12] | −0.2 | 0.35 | V |
| $V_{crossover}$ | CPU | Crossover Voltage | Measured with test loads[12] | 0.51 | 0.76 | V |
| **CPU 0.7V Switching Characteristics** | | | | | | |
| $t_2$ | CPU | Rise Time | Measured single ended waveform from 0.175V to 0.525V | 175 | 700 | ps |
| $t_3$ | CPU | Fall Time | Measured single ended waveform from 0.175V to 0.525V | 175 | 700 | ps |
| $t_4$ | CPU | CPU-CPU Skew | Measured at Crossover | | 150 | ps |
| $t_8$ | CPU | Cycle-Cycle Clock Jitter | Measured at Crossover $t_8 = t_{8A} - t_{8B}$ With all outputs running | | 150 | ps |
| | CPU | Rise/Fall Matching | Measured with test loads[11, 12] | | 20 | % |
| $V_{oh}$ | CPU | High-level Output Voltage Including Overshoot | Measured with test loads[12] | | 0.85 | V |
| $V_{ol}$ | CPU | Low-level Output Voltage Including Undershoot | Measured with test loads[12] | | −0.15 | V |
| $V_{crossover}$ | CPU | Crossover Voltage | Measured with test loads[12] | 0.28 | 0.43 | V |

**Notes:**
9. All parameters specified with loaded outputs.
10. Duty cycle is measured at 1.5V when $V_{DD}$ = 3.3V. When $V_{DD}$ = 2.5V, duty cycle is measured at 1.25V.
11. Determined as a fraction of 2*(Trp − Trn)/(Trp +Trn) Where Trp is a rising edge and Trp is an intersecting falling edge.
12. The 0.7V test load is $R_s$ = 33.2 ohm, $R_p$ = 49.9 ohm in test circuit.
13. The 1.0V test load is shown on the test circuit page.

**Definition and Application of PWRGD# Signal**
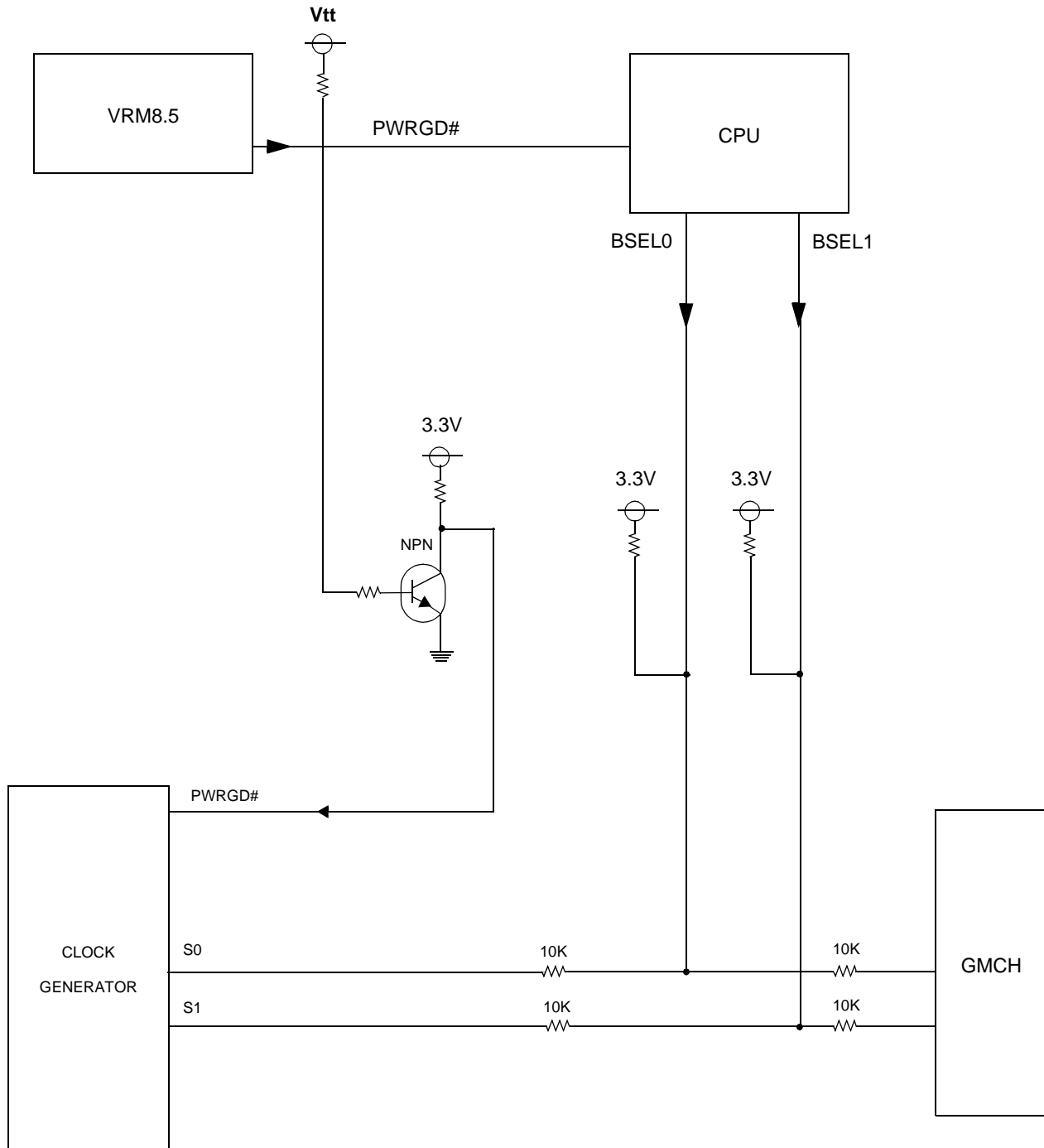
## Switching Waveforms

**Duty Cycle Timing** **(Single-ended Output)**

$t_{1B}$

$t_{1A}$

**Duty Cycle Timing (CPU Differential Output)**

$t_{1B}$

$t_{1A}$

**All Outputs Rise/Fall Time**

OUTPUT

$V_{DD}$

0V

$t_2$

$t_3$

**CPU-CPU Clock Skew**

Host_b

Host

Host_b

Host

$t_4$
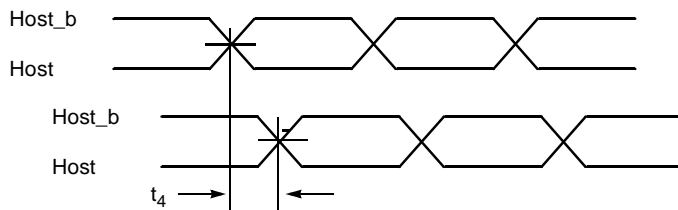
**3V66-3V66 Clock Skew**

3V66

3V66

**PCI-PCI Clock Skew**

PCI

PCI
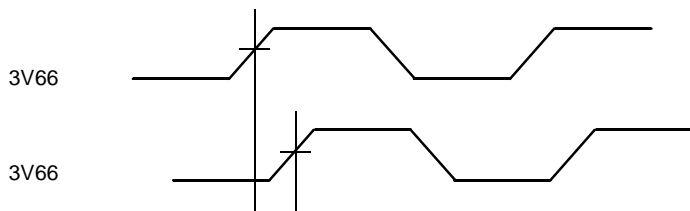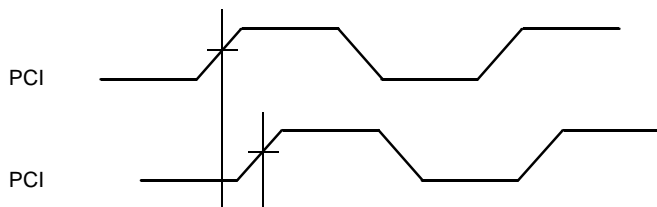
## Switching Waveforms   (continued)

**3V66-PCI Clock Skew**
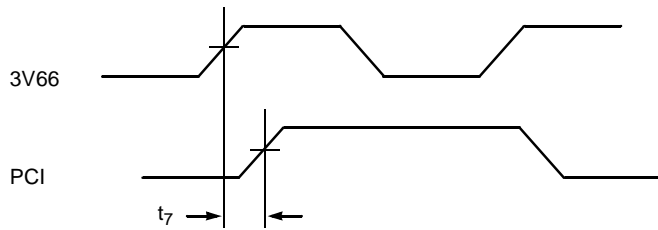


**CPU Clock Cycle-Cycle Jitter**
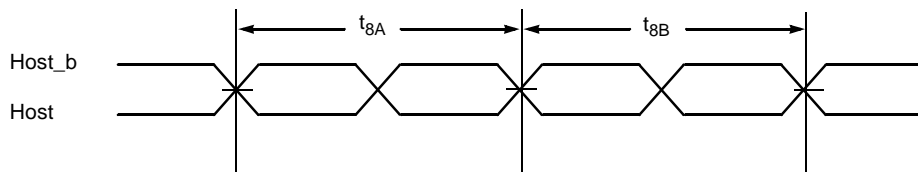


**Cycle-Cycle Clock Jitter**
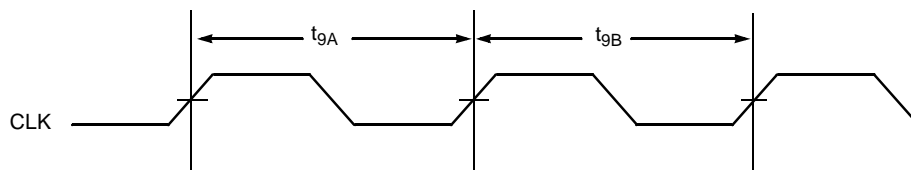


**PWRDWN# Assertion**
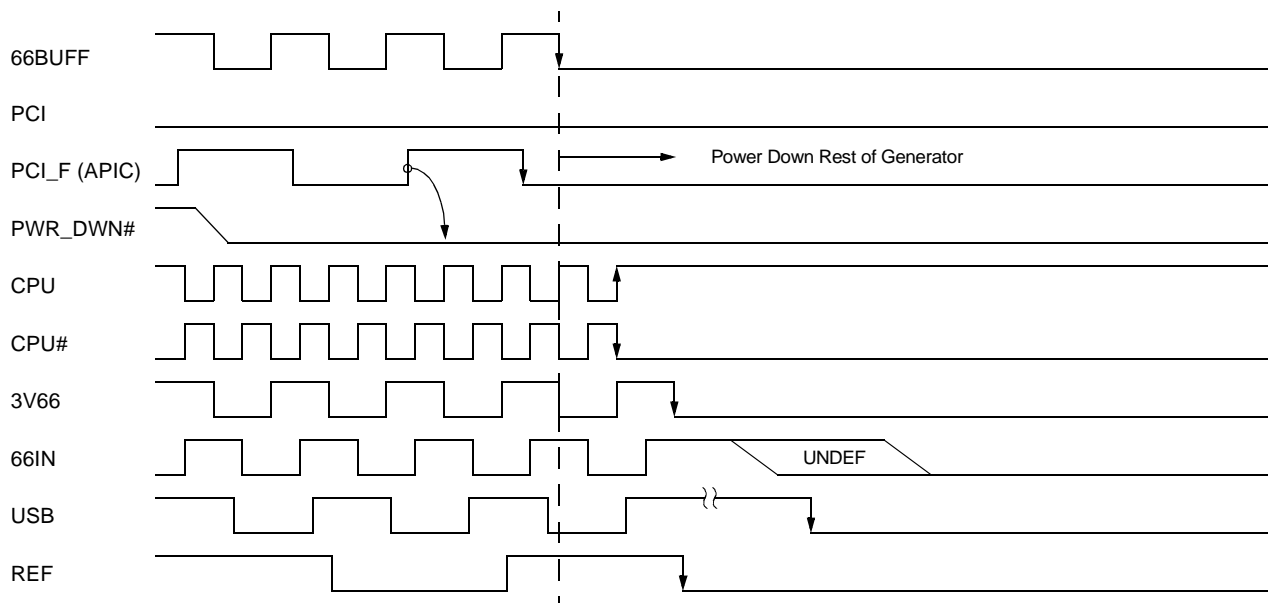


Note: PCI_STOP# asserted LOW

**PWRDWN# Deassertion**
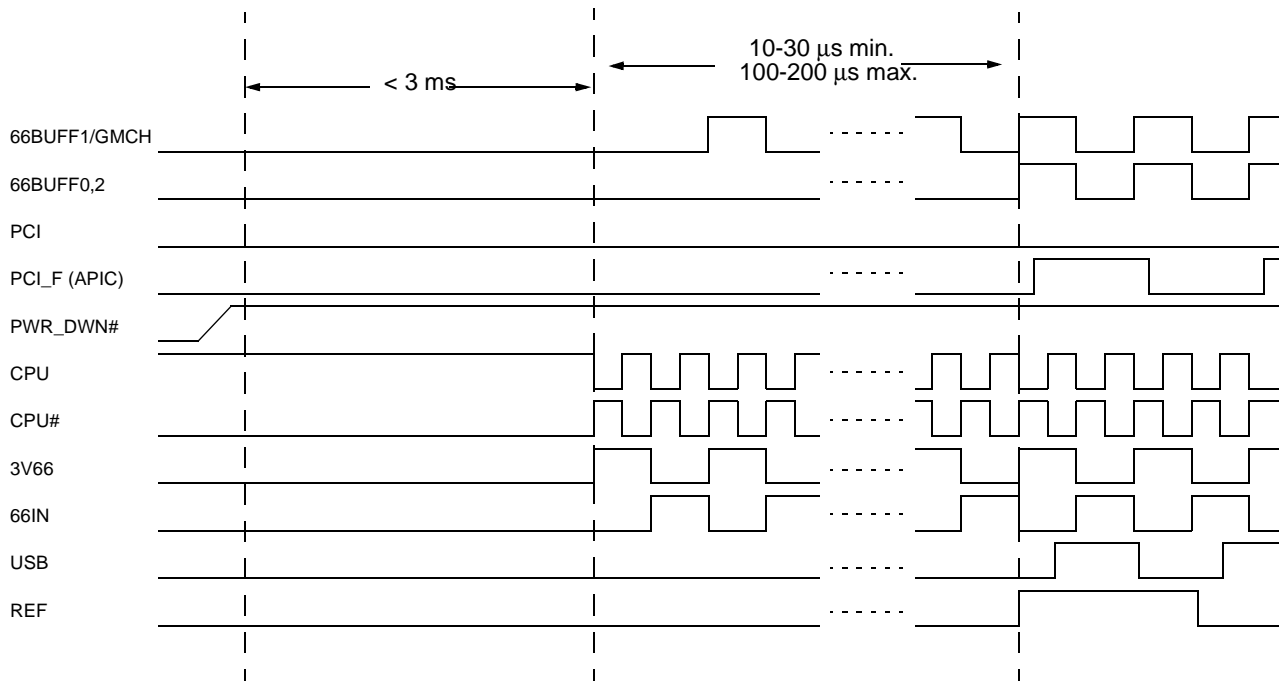


Note: PCI_STOP# asserted LOW

**PWRGD# Timing Diagrams**
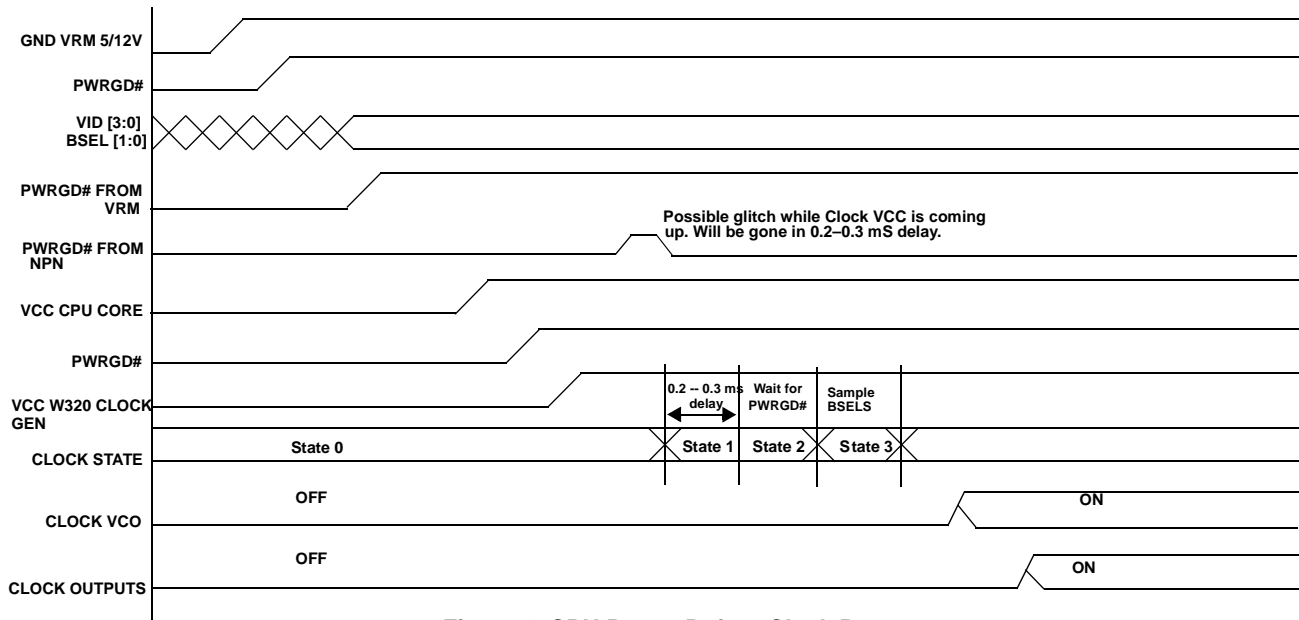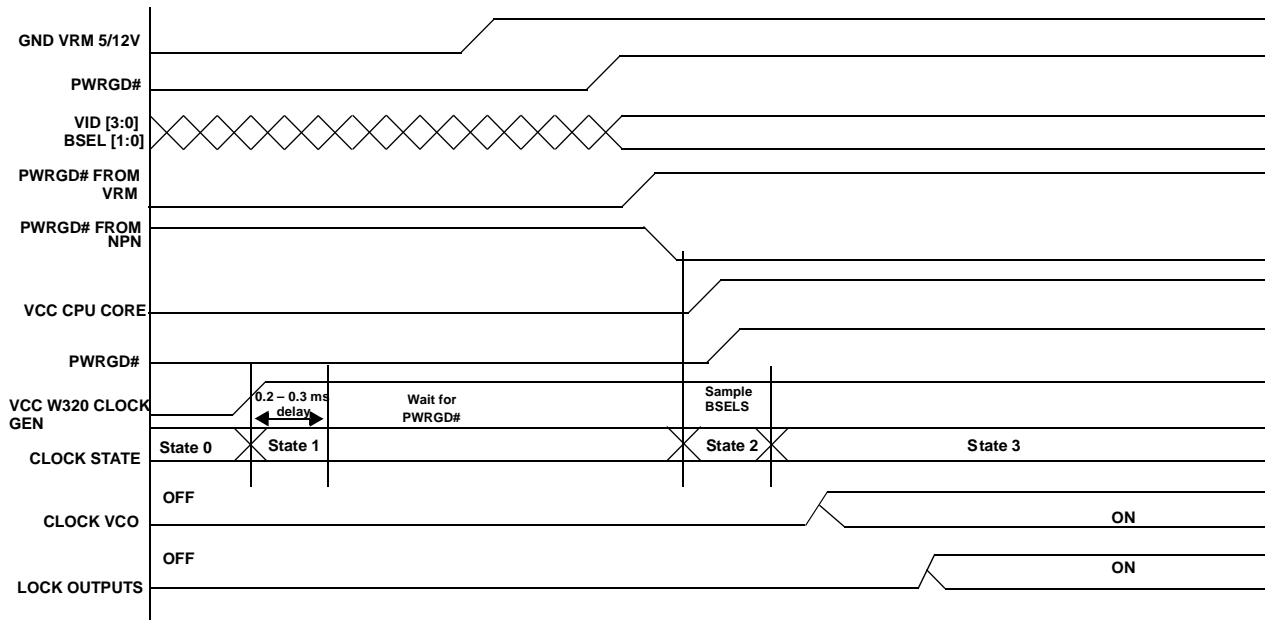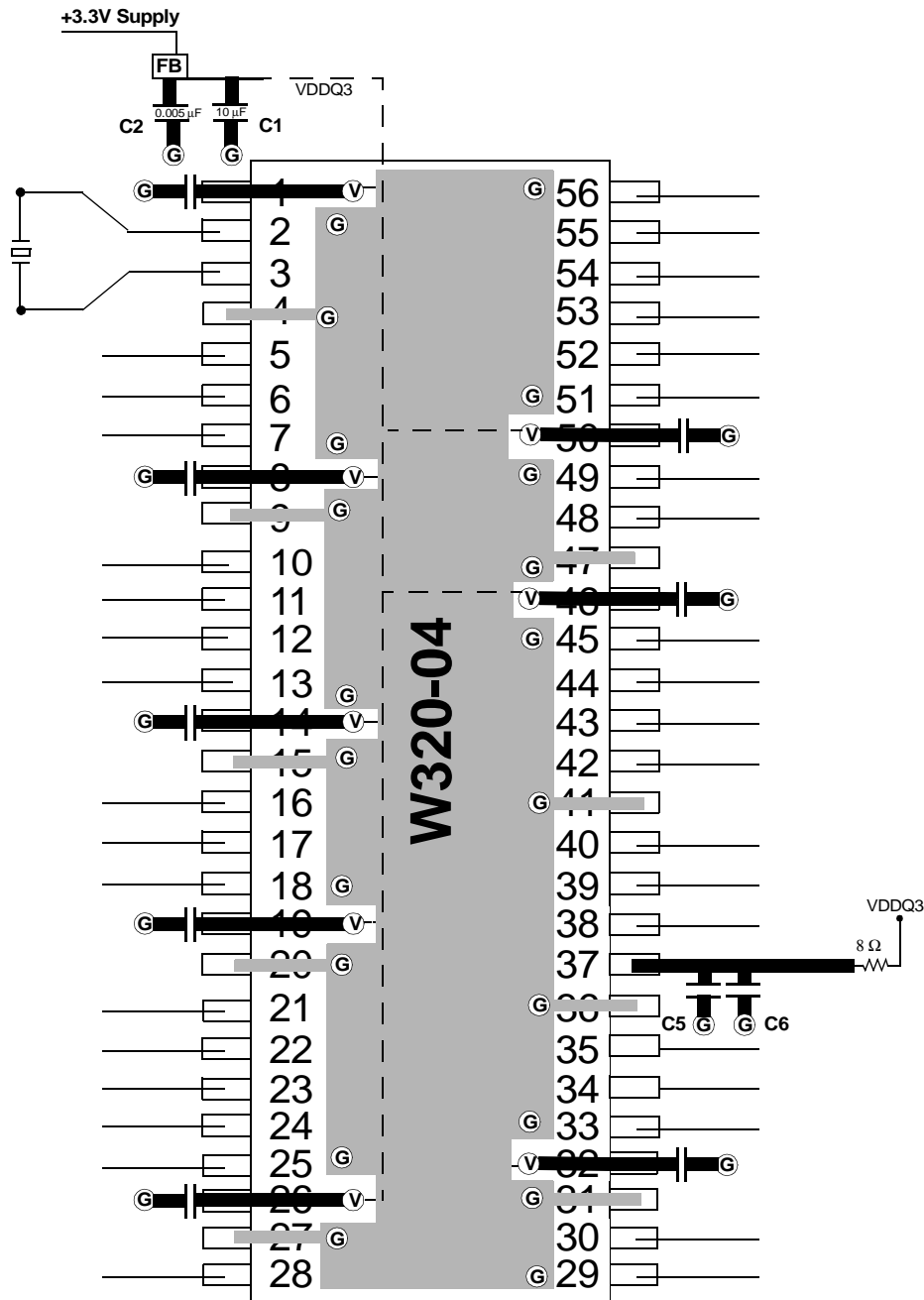


**Figure 2. CPU Power Before Clock Power**

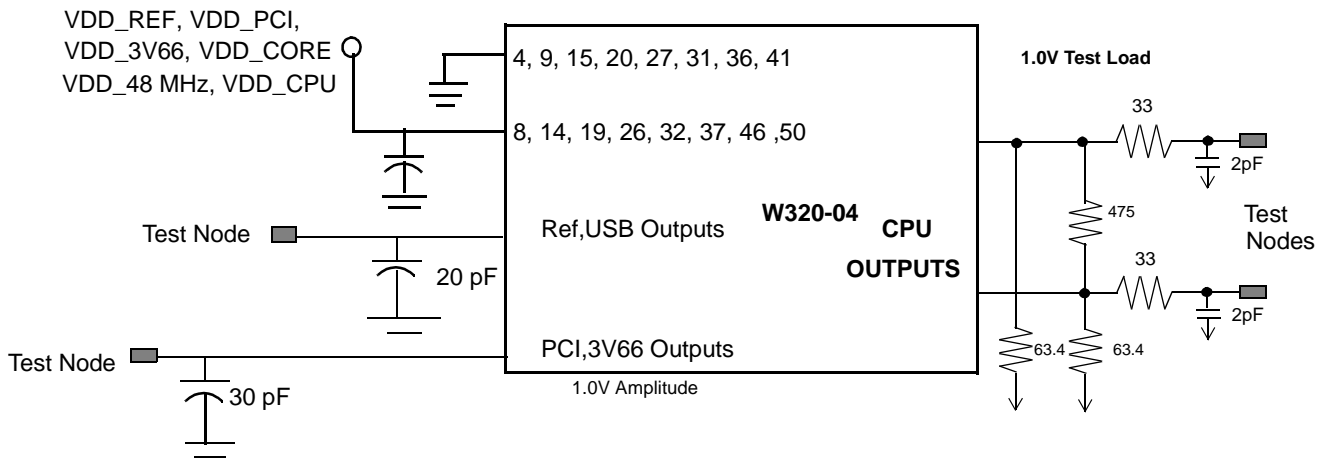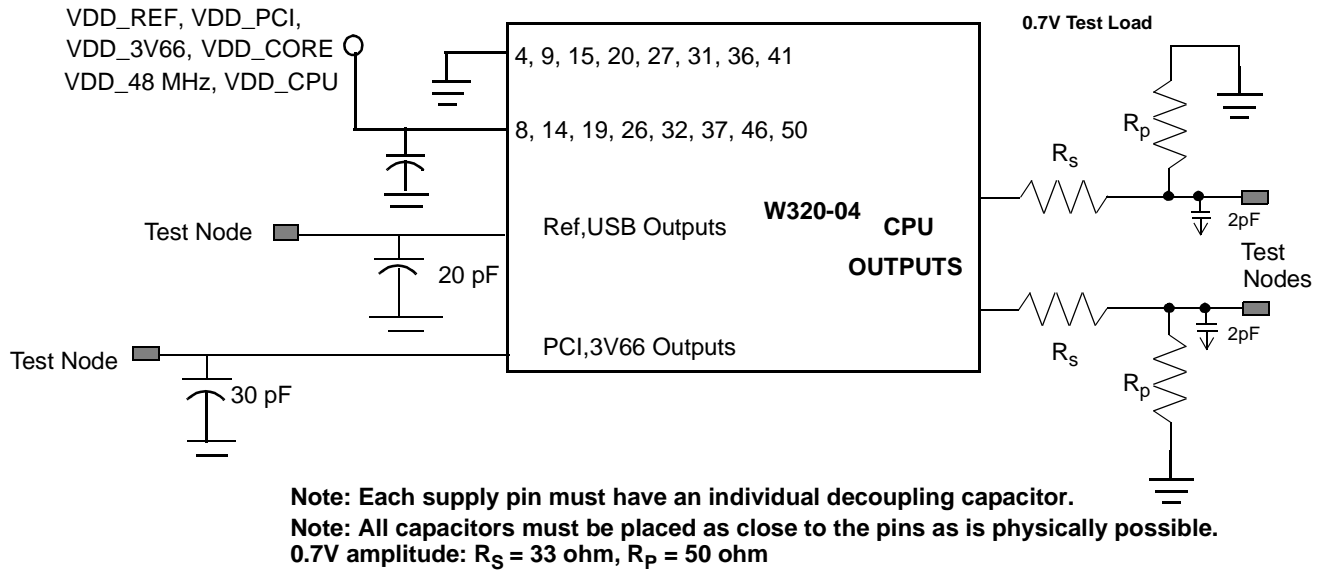**Figure 3. CPU Power After Clock Power**

## Layout Example



**FB = Dale ILB1206 - 300 or 2TDKACB2012L-120 or 2 Murata BLM21B601S.**

**Ceramic Caps  C1 = 10–22 $\mu$F C2 = 0.005 $\mu$F C5 = 0.1 $\mu$F C6 = 10 $\mu$F**

**ⓖ = VIA to GND plane layer.  Ⓥ = VIA to respective supply plane layer.**

**Note: Each supply plane or strip should have a ferrite bead and capacitors.**
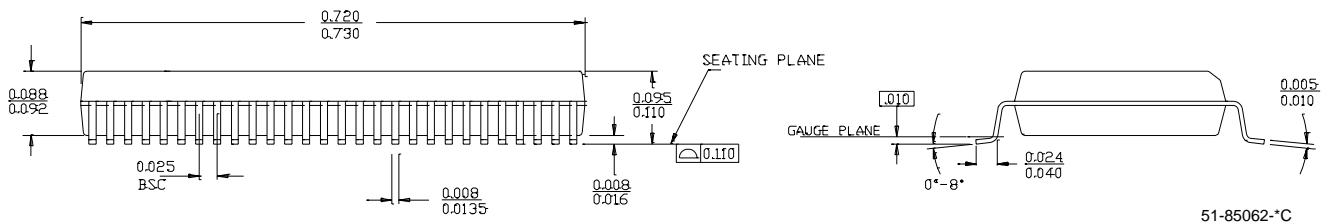
## Test Circuit



VDD_REF, VDD_PCI,
VDD_3V66, VDD_CORE
VDD_48 MHz, VDD_CPU

**0.7V Test Load**

4, 9, 15, 20, 27, 31, 36, 41

8, 14, 19, 26, 32, 37, 46, 50

Ref,USB Outputs    **W320-04**  **CPU**

**OUTPUTS**

PCI,3V66 Outputs

Test Node

20 pF

Test Node

30 pF

$R_s$  $R_p$  2pF

$R_s$  $R_p$  2pF

Test Nodes

**Note: Each supply pin must have an individual decoupling capacitor.**
**Note: All capacitors must be placed as close to the pins as is physically possible.**
**0.7V amplitude: $R_S$ = 33 ohm, $R_P$ = 50 ohm**

VDD_REF, VDD_PCI,
VDD_3V66, VDD_CORE
VDD_48 MHz, VDD_CPU

**1.0V Test Load**

4, 9, 15, 20, 27, 31, 36, 41

8, 14, 19, 26, 32, 37, 46 ,50

Ref,USB Outputs    **W320-04**  **CPU**

**OUTPUTS**

PCI,3V66 Outputs

1.0V Amplitude

Test Node

20 pF

Test Node

30 pF

33  2pF
475
33  2pF
63.4  63.4

Test Nodes

## Ordering Information

| Ordering Code | Package Type | Operating Range |
|---|---|---|
| W320-04H | 56-pin SSOP | Commercial 0°C TO 70°C |
| W320-04X | 56-pin TSSOP | |

## Package Diagrams

**56-Lead Shrunk Small Outline Package O56**
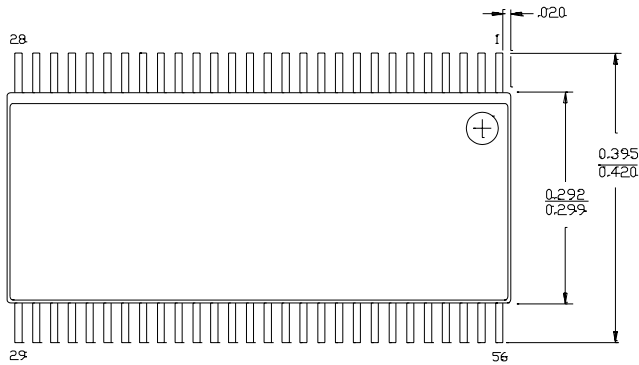


DIMENSIONS IN INCHES <u>MIN.</u>
MAX.

51-85062-*C

## Package Diagrams (continued)

### 56-Pin Thin Shrink Small Outline Package

TOP VIEW

END VIEW

BOTTOM VIEW

EVEN LEAD SIDES
TOP VIEW

ODD LEAD SIDES
TOP VIEW

X = A AND B

SIDE VIEW

SECTION "C–C"
SCALE: 120/1
(SEE NOTE 10)

WITH PLATING

BASE METAL

DETAIL "A"
(SCALE: 30/1)

DETAIL "B"
(SCALE: 30/1)
DAMBAR PROTRUSION
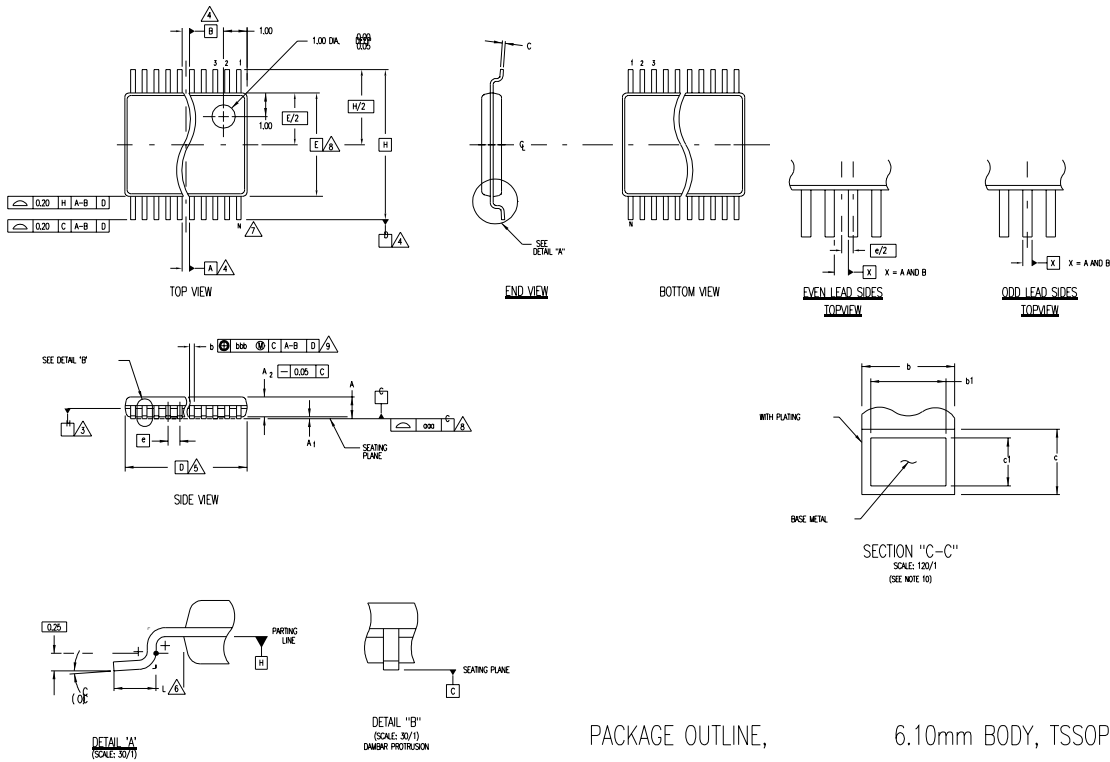
PACKAGE OUTLINE,        6.10mm BODY, TSSOP

PARTING LINE

SEATING PLANE

THIS TABLE FOR 0.50mm PITCH

| | COMMON DIMENSIONS | | | NOTE | VARI-ATIONS | | MIN. | NOM. | MAX. | N |
|---|---|---|---|---|---|---|---|---|---|---|
| | MIN. | NOM. | MAX. | | | | | | | |
| A | — | — | 1.10 | | ED | | 12.40 | 12.50 | 12.60 | 48 |
| A1 | 0.05 | — | 0.15 | | EE | | 13.90 | 14.00 | 14.10 | 56 |
| A2 | 0.80 | 1.00 | 1.05 | | EF* | | 16.80 | 17.00 | 17.10 | 64 |
| ccc | | 0.10 | | | | | | | | |
| b | 0.17 | — | 0.27 | 9 | *DESIGNED BUT NOT TOOLED | | | | | |
| b1 | 0.17 | 0.20 | 0.23 | | | | | | | |
| bbb | | 0.08 | | | | | | | | |
| c | 0.09 | | 0.20 | | | | | | | |
| c1 | 0.09 | 0.127 | 0.16 | | | | | | | |
| D | SEE VARIATIONS | | | 5 | | | | | | |
| E | 6.20 | 6.10 | 6.20 | 5 | | | | | | |
| e | 0.50 BSC | | | | | | | | | |
| H | 8.10 BSC | | | | | | | | | |
| L | 0.50 | 0.60 | 0.75 | 6 | | | | | | |
| N | SEE VARIATIONS | | | 7 | | | | | | |
| æ | 0 | — | 8 | 8 | | | | | | |

ALL DIMENSIONS IN MILLIMETERS

NOTES:
1. DIE THICKNESS ALLOWABLE IS 0.279±0.0127 (.011±.0005 INCHES)
2. DIMENSIONING & TOLERANCES PER ASME. Y14.5M–1994.
3. DATUM PLANE H LOCATED AT MOLD PARTING LINE AND COINCIDENT WITH LEAD, WHERE LEAD EXITS PLASTIC BODY AT BOTTOM OF PARTING LINE.
4. DATUMS A–B AND D TO BE DETERMINED WHERE CENTERLINE BETWEEN LEADS EXITS PLASTIC BODY AT DATUM PLANE H.
5. "D" & "E" ARE REFERENCE DATUMS AND DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS, AND ARE MEASURED AT THE BOTTOM PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15mm ON D AND 0.25mm ON E PER SIDE.
6. DIMENSION IS THE LENGTH OF TERMINAL FOR SOLDERING TO A SUBSTRATE.
7. TERMINAL POSITIONS ARE SHOWN FOR REFERENCE ONLY.
8. FORMED LEADS SHALL BE PLANAR WITH RESPECT TO ONE ANOTHER WITHIN 0.076mm AT SEATING PLANE.
9. THE LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08mm TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND AN ADJACENT LEAD TO BE 0.10MM FOR 0.65MM PITCH, 0.08MM FOR 0.50MM PITCH AND 0.07MM FOR 0.40MM PITCH PACKAGES. SEE DETAIL "B" AND SECTION "C–C".
10. SECTION "C–C" TO BE DETERMINED AT 0.10 TO 0.25 MM FROM THE LEAD TIP.
11. CONTROLLING DIMENSION: MILLIMETERS.
12. THIS PART IS COMPLIANT WITH JEDEC SPECIFICATION MO–153, VARIATIONS DB, DC, DE, ED, EE, AND FE.

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**Document Title: W320-04 200-MHz Spread Spectrum Clock Synthesizer/Driver with Differential CPU Outputs**
**Document Number: 38-07010**

| REV. | ECN NO. | Issue Date | Orig. of Change | Description of Change |
|---|---|---|---|---|
| ** | 106455 | 05/24/01 | IKA | New Data Sheet |
| *A | 111419 | 02/07/02 | IKA | Changes to Switching Characteristics Table |
| *B | 122716 | 12/21/02 | RBI | Added power up requirements to Operating Conditions information. |